SURFACE MOUNT SILICON SCHOTTKY DIODE



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMOSH-3 is a silicon Schottky diode, epoxy molded in an SOD-523 surface mount package, designed for fast switching applications requiring a low forward voltage drop.

MARKING CODE: 53



SOD-523 CASE

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	ΙF	100	mA
Peak Repetitive Forward Current	I _{FRM}	350	mA
Peak Forward Surge Current, tp=10ms	I _{FSM}	750	mA
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W

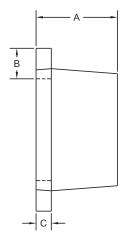
ELECTRICAL CHARACTERISTICS: (T _A =25°C unless otherwise noted)								
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS			
I_{R}	V _R =25V		90	500	nA			
I_{R}	V _R =25V, T _A =100°C		25	100	μΑ			
BV_R	I _R =100μA	30			V			
VF	I _F =2.0mA		0.29	0.33	V			
V_{F}	I _F =15mA		0.37	0.45	V			
V_{F}	I _F =100mA		0.51	1.00	V			
CJ	V _R =1.0V, f=1.0MHz		7.0		pF			
t _{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω			5.0	ns			

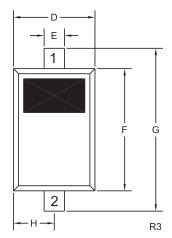
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SOD-523 CASE - MECHANICAL OUTLINE





LEAD CODE:

- 1) Cathode 2) Anode

MARKING CODE: 53

DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.020	0.031	0.50	0.80		
В	0.008	0.016	0.20	0.40		
С	0.002	0.008	0.05	0.20		
D	0.028	0.035	0.70	0.90		
E	0.008	0.014	0.20	0.35		
F	0.039	0.055	1.00	1.40		
G	0.055	0.071	1.40	1.80		
Н	0.016		0.40			
SOD-523 (REV: R3)						

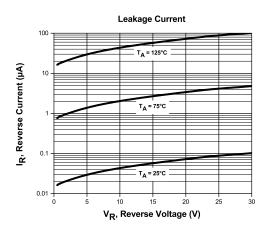
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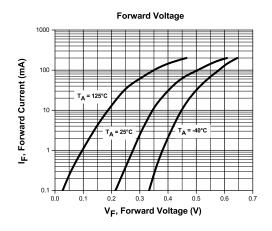
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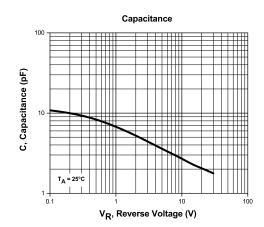
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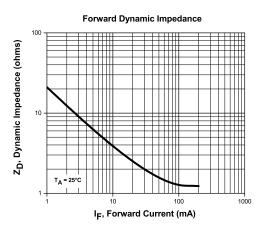


TYPICAL ELECTRICAL CHARACTERISTICS









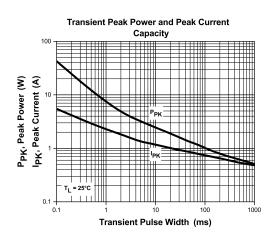
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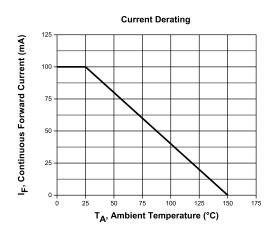
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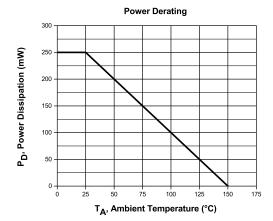
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TYPICAL ELECTRICAL CHARACTERISTICS







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PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- · Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- · PbSn plating options
- · Package details
- · Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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